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Vishay Semiconductors

RoHS

COMPLIANT

HALOGEN FREE

GREEN

High Speed Infrared Emitting Diodes, 850 nm, Surface Emitter Technology



LINKS TO ADDITIONAL RESOURCES



DESCRIPTION

As part of the <u>SurfLight</u>TM portfolio, the VSMY2853 series are infrared, 850 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

FEATURES

Package type: surface-mountPackage form: GW, RGW



Peak wavelength: λ_p = 850 nm

· High reliability

· High radiant power

· Very high radiant intensity

• Angle of half intensity: $\varphi = \pm 28^{\circ}$

· Suitable for high pulse current operation

· Terminal configurations: gullwing or reverse gullwing

• Package matches with detector VEMD2503X01 series

• Floor life: 4 weeks, MSL 2a, according to J-STD-020

 Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

APPLICATIONS

- · Miniature light barrier
- Photointerrupters
- · Optical switch
- Emitter source for proximity sensors
- IR touch panels
- IR illumination
- Smart metering

PRODUCT SUMMARY					
COMPONENT	I _e (mW/sr)	φ (°)	$λ_p$ (nm)	t _r (ns)	
VSMY2853RG	50	± 28	850	10	
VSMY2853G	50	± 28	850	10	

Note

· Test conditions see table "Basic Characteristics"

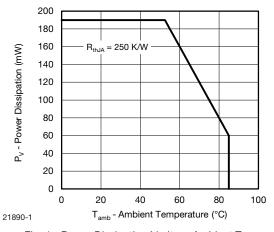
ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM		
VSMY2853RG	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing		
VSMY2853G	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing		

Note

• MOQ: minimum order quantity



ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
Reverse voltage		V _R	5	V	
Forward current		I _F	100	mA	
Peak forward current	$t_p/T = 0.5, t_p = 100 \mu s$	I _{FM}	200	mA	
Surge forward current	t _p = 100 μs	I _{FSM}	1	Α	
Power dissipation		P _V	190	mW	
Junction temperature		T _j	100	°C	
Operating temperature range		T _{amb}	-40 to +85	°C	
Storage temperature range		T _{stg}	-40 to +100	°C	
Soldering temperature	According to Fig. 7, J-STD-020	T _{sd}	260	°C	
Thermal resistance junction to ambient	EIA / JESD51	R _{thJA}	250	K/W	



100 I_F - Forward Current (mA) 80 $R_{thJA} = 250 \text{ K/W}$ 60 40 20 0 0 20 40 60 80 100 T_{amb} - Ambient Temperature (°C) 21891-1

Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Farmer describer of	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	V _F	-	1.6	1.9	V
Forward voltage	$I_F = 1 \text{ A}, t_p = 100 \mu \text{s}$	V_{F}	-	2.8	-	V
Temperature coefficient of V _F	I _F = 100 mA	TK _{VF}	-	-1.5	-	mV/K
Reverse current		I _R	Not designed for reverse operation µA		μΑ	
Junction capacitance	$V_R = 0 \text{ V, f} = 1 \text{ MHz, E} = 0 \text{ mW/cm}^2$	CJ	-	50	-	pF
Radiant intensity	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	l _e	27	50	75	mW/sr
	$I_F = 1 \text{ A}, t_p = 100 \mu \text{s}$	l _e	-	350	-	mW/sr
Radiant power	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	фe	-	55	-	mW
Temperature coefficient of radiant power	I _F = 100 mA	TΚφ _e	-	-0.12	-	%/K
Angle of half intensity		φ	-	± 28	-	0
Peak wavelength	I _F = 100 mA	λ_{p}	840	850	870	nm
Spectral bandwidth	I _F = 30 mA	Δλ	-	30	-	nm
Temperature coefficient of λ _p	I _F = 30 mA	TKλ _p	-	0.25	-	nm/K
Rise time	I _F = 100 mA, 10 % to 90 %	t _r	-	10	-	ns
Fall time	I _F = 100 mA, 10 % to 90 %	t _f	-	10	-	ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

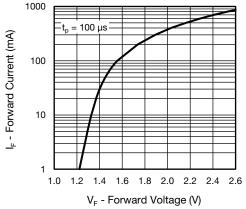


Fig. 3 - Forward Current vs. Forward Voltage

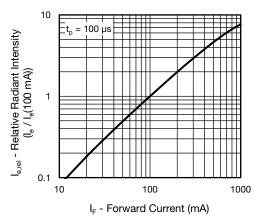


Fig. 4 - Relative Radiant Intensity vs. Forward Current

SOLDER PROFILE

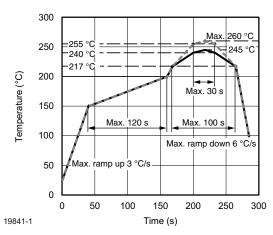


Fig. 7 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

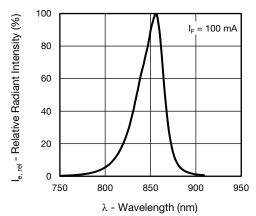


Fig. 5 - Relative Radiant Power vs. Wavelength

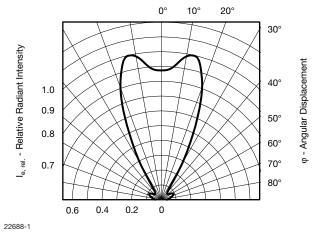


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

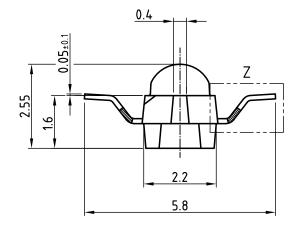
Conditions: T_{amb} < 30 °C, RH < 60 %

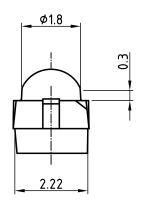
Moisture sensitivity level 2a, according to J-STD-020.

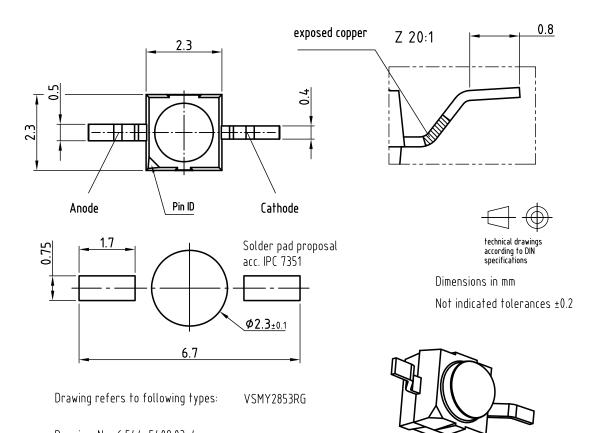
DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ M.

PACKAGE DIMENSIONS in millimeters: VSMY2853RG



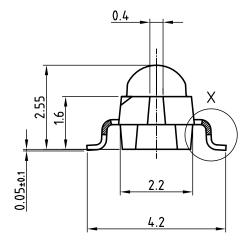


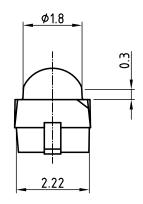


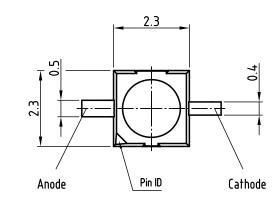
Drawing-No.: 6.544-5409.03-4

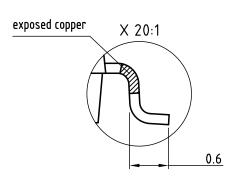
Issue: prel. 03.08.12

PACKAGE DIMENSIONS in millimeters: VSMY2853G









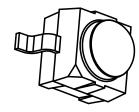


Solder pad proposal
acc. IPC 7351

2.45
5.15

Dimensions in mm

Not indicated tolerances ±0.2

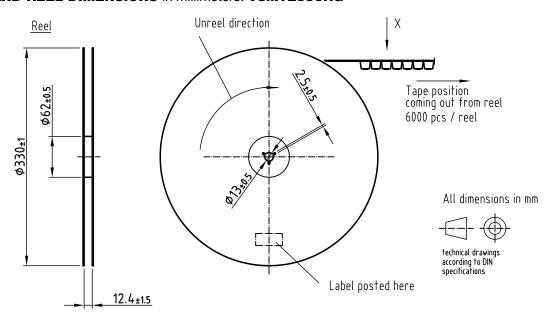


Drawing refers to following types: VSMY2853G

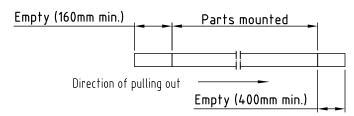
Drawing-No.: 6.544-5408.03-4

Issue: prel; 03.08.12

TAPING AND REEL DIMENSIONS in millimeters: VSMY2853RG

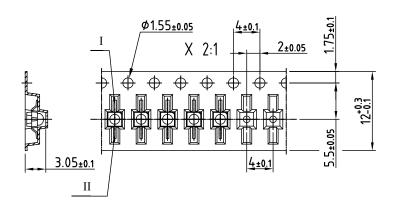


Leader and trailer tape:



Terminal position in tape

Device	Lead I	Lead II	
VSMB2943RGX01		Anode	
VSMF2893RGX01	Cathode		
VEMD2x03X01	Carnoue		
VEMT2x03X01	Collector	Emitter	
	Collector	Lillinei	
VSMY2853RG	Anode	Cathode	

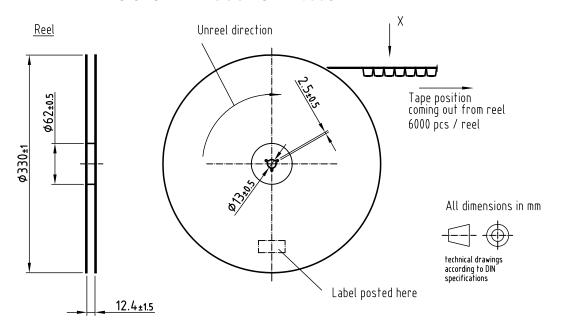


Drawing refers to following types: Reel dimensions and tape see table

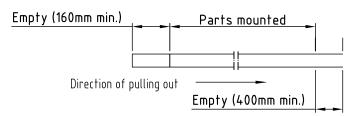
Drawing-No.: 9.800-5100.02-4 Issue: prel; 03.08.12



TAPING AND REEL DIMENSIONS in millimeters: VSMY2853G

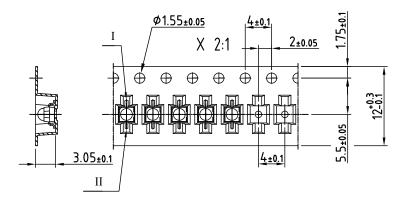


Leader and trailer tape:



Terminal position in tape

Device	Lead I	Lead II	
VSMB2943GX01			
VSMF2893GX01	Cathode	Anode	
VEMD2x23X01	Carriode	Alloue	
VEMT2x23X01	Collector	Emitter	
	Collector	Ellitter	
VSMY2853G	Anode	Cathode	



Drawing refers to following types: see table

Reel dimensions and tape

Drawing-No.: 9.800-5091.21-4

Issue: prel; 03.08.12



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